## 1. Scope :

This specification applies to silicon switching diode chips,
Device No. SD-0013.

## 2. Structure :

2-1. Mesa type.
2-2. Electrodes:
P (Anode ) Side: Aluminum alloy.
N (Cathode) Side: Gold alloy.

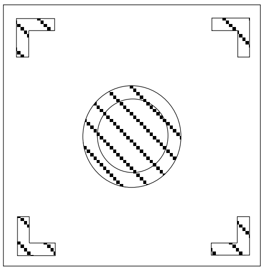
## 3. Size :

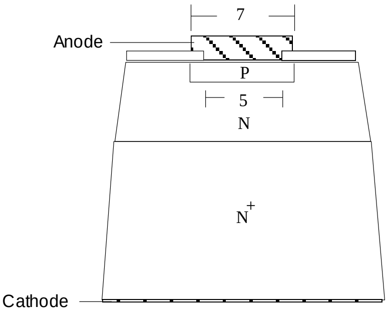
3-1. Chip size: 13 mils x 13 mils (0.330 mm x 0.330 mm).
3-2. Chip Thickness: 7.5 mils ± 1.5 mils (0.191 mm ± 0.038 mm).
3-3. Pattern drawing: Refer to the attached drawing.

## 4. Electrical characteristics (Ta = 25 ℃)

| Parameter | Symbol | Condition | Min. | Typ. | Max. | Unit |
|---|---|---|---|---|---|---|
| Forward Voltage | $V_F$ | $I_F$=10mA<br>Ee=0mW/cm$^2$ | 0.77 | 0.82 | 0.87 | V |
| Reverse Current | $I_R$ | $V_R$=80V<br>Ee=0mW/cm$^2$ | | 0.5 | 1.0 | µA |
| Reverse Breakdown Voltage | $V_{(BV)R}$ | $I_R$=5µA<br>Ee=0mW/cm$^2$ | 100 | | | V |

PATTERN DRAWING
UNIT: mil





## 5. Packing and labeling :

5-1. Packing :
Two types can be chosen:
PSA :Sheet type
Each pellet is mounted on an adhesive sheet
With wire-bonded electrode side up.
NS :Sheet type
Each pellet is mounted on an adhesive sheet
With back electrode side up.

5-2. Labeling :
Each lot has a label sheet, writting type, lot no,
PCS,avg. , and quantity of good chips.